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What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	925MHz
Primary Attributes	FPGA - 85K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5csema5f31c6n



Cyclone V Device Datasheet

This datasheet describes the electrical characteristics, switching characteristics, configuration specifications, and I/O timing for Cyclone® V devices.

Cyclone V devices are offered in commercial and industrial grades. Commercial devices are offered in –C6 (fastest), –C7, and –C8 speed grades. Industrial grade devices are offered in the –I7 speed grade. Automotive devices are offered in the –A7 speed grade.

Cyclone V SoC devices are also offered in a low-power variant, as indicated by the L power option in the device part number. These devices have 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE. Note that the L power option devices are only available in –I7 speed grade, and have the equivalent operating conditions and timing specifications as the standard –I7 speed grade devices.

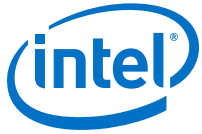
Table 1. Low Power Variants

Density	Ordering Part Number (OPN)	Static Power Reduction
25K LE	5CSEBA2U19I7LN	30%
	5CSEBA2U23I7LN	
	5CSXFC2C6U23I7LN	
40K LE	5CSEBA4U19I7LN	30%
	5CSEBA4U23I7LN	
	5CSXFC4C6U23I7LN	
85K LE	5CSEBA5U19I7LN	20%
	5CSEBA5U23I7LN	
	5CSXC5C6U23I7LN	

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*Other names and brands may be claimed as the property of others.



Density	Ordering Part Number (OPN)	Static Power Reduction
110K LE	5CSEBA6U19I7LN	
	5CSEBA6U23I7LN	
	5CSXFC6C6U23I7LN	

To estimate total power consumption for a low-power device, listed in [Table 1](#) on page 3:

1. Multiply the Total Static Power reported by the Early Power Estimator (EPE) by the appropriate scale factor:
 - For 25K LE and 40K LE devices, use 0.7
 - For 85K LE and 110K LE devices, use 0.8
2. Add the result from Step 1 on page 4 to the Total Dynamic Power reported by the EPE.

Related Information

[Cyclone V Device Overview](#)

Provides more information about the densities and packages of devices in the Cyclone V family.

Electrical Characteristics

The following sections describe the operating conditions and power consumption of Cyclone V devices.

Operating Conditions

Cyclone V devices are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of the Cyclone V devices, you must consider the operating requirements described in this section.

Absolute Maximum Ratings

This section defines the maximum operating conditions for Cyclone V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms.

The functional operation of the device is not implied for these conditions.

Caution: Conditions outside the range listed in the following table may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.



Symbol	Description	Condition	Minimum ⁽¹¹⁾	Typical	Maximum ⁽¹¹⁾	Unit
		1.8 V	1.71	1.8	1.89	V
V _{CCPLL_HPS}	HPS PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V _{CC_AUX_SHARED} ⁽¹⁴⁾	HPS auxiliary power supply	—	2.375	2.5	2.625	V

Related Information

[Recommended Operating Conditions](#) on page 8

Provides the steady-state voltage values for the FPGA portion of the device.

DC Characteristics

Supply Current and Power Consumption

Intel offers two ways to estimate power for your design—the Excel-based EPE and the Intel® Quartus® Prime Power Analyzer feature.

Use the Excel-based EPE before you start your design to estimate the supply current for your design. The EPE provides a magnitude estimate of the device power because these currents vary greatly with the resources you use.

The Intel Quartus Prime Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

Related Information

- [Early Power Estimator User Guide](#)
Provides more information about power estimation tools.
- [Power Analysis chapter, Intel Quartus Prime Handbook](#)
Provides more information about power estimation tools.

⁽¹¹⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽¹⁴⁾ V_{CC_AUX_SHARED} must be powered by the same source as V_{CC_AUX} for Cyclone V SX C5, C6, D5, and D6 devices, and Cyclone V SE A5 and A6 devices.



I/O Standard	V _{CCIO} (V)			V _{REF} (V)			V _{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-15 Class I, II	1.425	1.5	1.575	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-135 Class I, II	1.283	1.35	1.418	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-125 Class I, II	1.19	1.25	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	—	$V_{CCIO}/2$	—
HSUL-12	1.14	1.2	1.3	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	—	—	—

Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications

Table 17. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Cyclone V Devices

I/O Standard	V _{IL(DC)} (V)		V _{IH(DC)} (V)		V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{OL} ⁽¹⁹⁾ (mA)	I _{OH} ⁽¹⁹⁾ (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.608$	$V_{TT} + 0.608$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.81$	$V_{TT} + 0.81$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.603$	$V_{TT} + 0.603$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4

continued...

(19) To meet the I_{OL} and I_{OH} specifications, you must set the current strength settings accordingly. For example, to meet the SSTL15CI specification (8 mA), you should set the current strength settings to 8 mA. Setting at lower current strength may not meet the I_{OL} and I_{OH} specifications in the datasheet.



Differential SSTL I/O Standards

Table 18. Differential SSTL I/O Standards for Cyclone V Devices

I/O Standard	V _{CCIO} (V)			V _{SWING(DC)} (V)		V _{X(AC)} (V)			V _{SWING(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.2	—	V _{CCIO} /2 + 0.2	0.62	V _{CCIO} + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.175	—	V _{CCIO} /2 + 0.175	0.5	V _{CCIO} + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	⁽²⁰⁾	V _{CCIO} /2 - 0.15	—	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	2(V _{IL(AC)} - V _{REF})
SSTL-135	1.283	1.35	1.45	0.18	⁽²⁰⁾	V _{CCIO} /2 - 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	2(V _{IL(AC)} - V _{REF})
SSTL-125	1.19	1.25	1.31	0.18	⁽²⁰⁾	V _{CCIO} /2 - 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	2(V _{IL(AC)} - V _{REF})

Differential HSTL and HSUL I/O Standards

Table 19. Differential HSTL and HSUL I/O Standards for Cyclone V Devices

I/O Standard	V _{CCIO} (V)			V _{DIF(DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	—	0.5 × V _{CCIO}	—	0.4 × V _{CCIO}	0.5 × V _{CCIO}	0.6 × V _{CCIO}	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5 × V _{CCIO} - 0.12	0.5 × V _{CCIO}	0.5 × V _{CCIO} + 0.12	0.4 × V _{CCIO}	0.5 × V _{CCIO}	0.6 × V _{CCIO}	0.44	0.44

⁽²⁰⁾ The maximum value for V_{SWING(DC)} is not defined. However, each single-ended signal needs to be within the respective single-ended limits (V_{IH(DC)} and V_{IL(DC)}).



Differential I/O Standard Specifications

Table 20. Differential I/O Standard Specifications for Cyclone V Devices

Differential inputs are powered by V_{CCPD} which requires 2.5 V.

I/O Standard	V_{CCIO} (V)			V_{ID} (mV) ⁽²¹⁾			$V_{ICM(DC)}$ (V)			V_{OD} (V) ⁽²²⁾			V_{OCM} (V) ⁽²²⁾⁽²³⁾		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
PCML	Transmitter, receiver, and input reference clock pins of high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to <i>Transceiver Specifications for Cyclone V GX, GT, SX, and ST Devices</i> table.														
2.5 V LVDS ⁽²⁴⁾	2.375	2.5	2.625	100	$V_{CM} = 1.25$ V	—	0.05	$D_{MAX} \leq 700$ Mbps	1.80	0.247	—	0.6	1.125	1.25	1.375
							1.05	$D_{MAX} > 700$ Mbps	1.55						
BLVDS ⁽²⁵⁾⁽²⁶⁾	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—	—
RSDS (HIO) ⁽²⁷⁾	2.375	2.5	2.625	100	$V_{CM} = 1.25$ V	—	0.25	—	1.45	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (HIO) (28)	2.375	2.5	2.625	200	—	600	0.300	—	1.425	0.25	—	0.6	1	1.2	1.4
<i>continued...</i>															

(21) The minimum V_{ID} value is applicable over the entire common mode range, V_{CM} .

(22) R_L range: $90 \leq R_L \leq 110 \Omega$.

(23) This applies to default pre-emphasis setting only.

(24) For optimized LVDS receiver performance, the receiver voltage input range must be within 1.0 V to 1.6 V for data rate above 700 Mbps and 0.00 V to 1.85 V for data rate below 700 Mbps.

(25) There are no fixed V_{ICM} , V_{OD} , and V_{OCM} specifications for BLVDS. They depend on the system topology.

(26) For more information about BLVDS interface support in Intel devices, refer to *AN522: Implementing Bus LVDS Interface in Supported Intel Device Families*.

(27) For optimized RSDS receiver performance, the receiver voltage input range must be within 0.25 V to 1.45 V.

(28) For optimized mini-LVDS receiver performance, the receiver voltage input range must be within 0.300 V to 1.425 V.



Symbol/Description	Condition	Transceiver Speed Grade 5 ⁽³⁰⁾			Transceiver Speed Grade 6			Transceiver Speed Grade 7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Intra-differential pair skew	TX V_{CM} = 0.65 V and slew rate of 15 ps	—	—	15	—	—	15	—	—	15	ps
Intra-transceiver block transmitter channel-to-channel skew	×6 PMA bonded mode	—	—	180	—	—	180	—	—	180	ps
Inter-transceiver block transmitter channel-to-channel skew	×N PMA bonded mode	—	—	500	—	—	500	—	—	500	ps

Table 25. CMU PLL Specifications for Cyclone V GX, GT, SX, and ST Devices

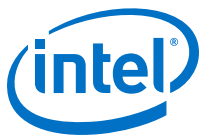
Symbol/Description	Condition	Transceiver Speed Grade 5 ⁽³⁰⁾			Transceiver Speed Grade 6			Transceiver Speed Grade 7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Supported data range	—	614	—	5000/6144 ⁽³⁵⁾	614	—	3125	614	—	2500	Mbps
fPLL supported data range	—	614	—	3125	614	—	3125	614	—	2500	Mbps

Table 26. Transceiver-FPGA Fabric Interface Specifications for Cyclone V GX, GT, SX, and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 5 ⁽³⁰⁾			Transceiver Speed Grade 6			Transceiver Speed Grade 7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Interface speed (single-width mode)	—	25	—	187.5	25	—	187.5	25	—	163.84	MHz
Interface speed (double-width mode)	—	25	—	163.84	25	—	163.84	25	—	156.25	MHz

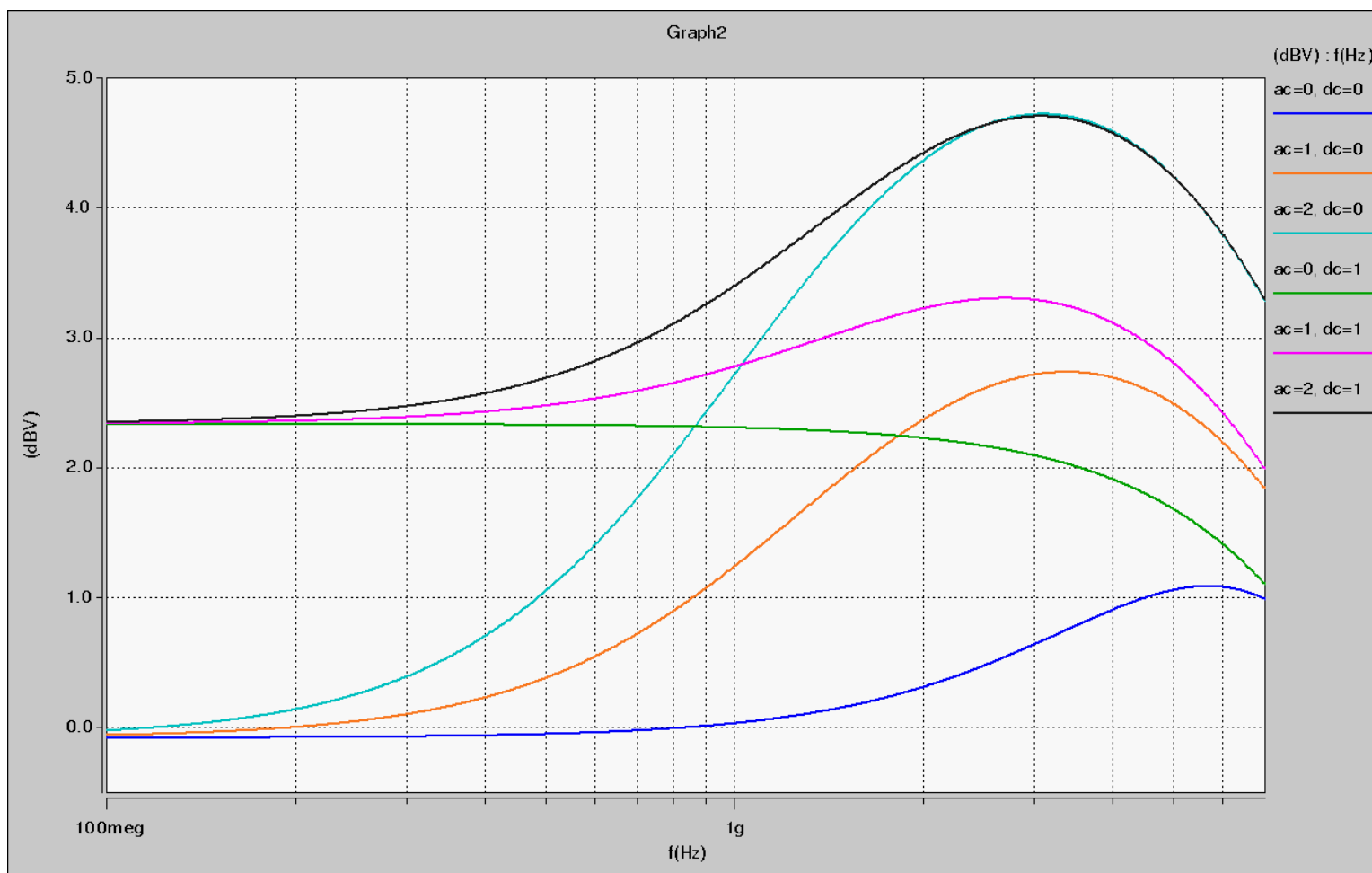
Related Information

- [CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain](#) on page 32
- [CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain](#) on page 33
- [PCIe Supported Configurations and Placement Guidelines](#)
Provides more information about the maximum full duplex channels recommended in Cyclone V GT and ST devices which require full compliance to the PCIe Gen2 transmit jitter specification.



CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain

Figure 3. Continuous Time-Linear Equalizer (CTLE) Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain for Cyclone V GX, GT, SX, and ST Devices





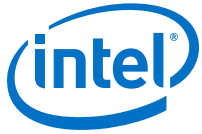
Protocol	Sub-protocol	Data Rate (Mbps)
	CPRI E12LV	1,228.8
	CPRI E12HV	1,228.8
	CPRI E12LVII	1,228.8
	CPRI E24LV	2,457.6
	CPRI E24LVII	2,457.6
	CPRI E30LV	3,072
	CPRI E30LVII	3,072
	CPRI E48LVII ⁽⁵¹⁾	4,915.2
	CPRI E60LVII ⁽⁵¹⁾	6,144
Gbps Ethernet (GbE)	GbE 1250	1,250
OBSAI	OBSAI 768	768
	OBSAI 1536	1,536
	OBSAI 3072	3,072
Serial digital interface (SDI)	SDI 270 SD	270
	SDI 1485 HD	1,485
	SDI 2970 3G	2,970
VbyOne	VbyOne 3750	3,750
HiGig+	HIGIG 3750	3,750

Related Information

- [PCIe Supported Configurations and Placement Guidelines](#)

Provides more information about the maximum full duplex channels recommended in Cyclone V GT and ST devices which require full compliance to the PCIe Gen2 transmit jitter specification.

⁽⁵¹⁾ For CPRI E48LVII and E60LVII, Intel recommends increasing the $V_{CC\bar{E}}_{GXBL}$ and $V_{CC\bar{L}}_{GXBL}$ typical value from 1.1 V to 1.2 V for full compliance to CPRI transmit jitter specification at 4.9152 Gbps (Cyclone V GT and ST devices) and 6.144 Gbps (Cyclone V GT and ST devices only). For more information about the maximum full duplex channels recommended in Cyclone V GT and ST devices for CPRI 6.144 Gbps, refer to the *Transceiver Protocol Configurations in Cyclone V Devices* chapter.



High-Speed I/O Specifications

Table 34. High-Speed I/O Specifications for Cyclone V Devices

When J = 1 or 2, bypass the serializer/deserializer (SERDES) block.

For LVDS applications, you must use the PLLs in integer PLL mode. This is achieved by using the LVDS clock network.

The Cyclone V devices support the following output standards using true LVDS output buffer types on all I/O banks.

- True RSDS output standard with data rates of up to 360 Mbps
- True mini-LVDS output standard with data rates of up to 400 Mbps

Symbol		Condition	-C6			-C7, -I7			-C8, -A7			Unit
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f _{HCLK_in} (input clock frequency) True Differential I/O Standards		Clock boost factor W = 1 to 40 ⁽⁶³⁾	5	—	437.5	5	—	420	5	—	320	MHz
f _{HCLK_in} (input clock frequency) Single-Ended I/O Standards		Clock boost factor W = 1 to 40 ⁽⁶³⁾	5	—	320	5	—	320	5	—	275	MHz
f _{HCLK_OUT} (output clock frequency)		—	5	—	420	5	—	370	5	—	320	MHz
Transmitter	True Differential I/O Standards - f _{HSDR} (data rate)	SERDES factor J = 4 to 10 ⁽⁶⁴⁾	⁽⁶⁵⁾	—	840	⁽⁶⁵⁾	—	740	⁽⁶⁵⁾	—	640	Mbps
<i>continued...</i>												

⁽⁶³⁾ Clock boost factor (W) is the ratio between the input data rate and the input clock rate.

⁽⁶⁴⁾ The F_{max} specification is based on the fast clock used for serial data. The interface F_{max} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.

⁽⁶⁵⁾ The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.



DLL Frequency Range Specifications

Table 35. DLL Frequency Range Specifications for Cyclone V Devices

Parameter	-C6	-C7, -I7	-C8	Unit
DLL operating frequency range	167 – 400	167 – 400	167 – 333	MHz

DQS Logic Block Specifications

Table 36. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Cyclone V Devices

This error specification is the absolute maximum and minimum error.

Number of DQS Delay Buffer	-C6	-C7, -I7	-C8	Unit
2	40	80	80	ps

Memory Output Clock Jitter Specifications

Table 37. Memory Output Clock Jitter Specifications for Cyclone V Devices

The memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2/DDR3 SDRAM standard.

The memory output clock jitter is applicable when an input jitter of 30 ps (p-p) is applied with bit error rate (BER) 10^{-12} , equivalent to 14 sigma.

Intel recommends using the UniPHY intellectual property (IP) with PHYCLK connections for better jitter performance.

Parameter	Clock Network	Symbol	-C6		-C7, -I7		-C8		Unit
			Min	Max	Min	Max	Min	Max	
Clock period jitter	PHYCLK	$t_{JIT(per)}$	-60	60	-70	70	-70	70	ps
Cycle-to-cycle period jitter	PHYCLK	$t_{JIT(cc)}$	—	90	—	100	—	100	ps



Duty Cycle Distortion (DCD) Specifications

Table 39. Worst-Case DCD on Cyclone V I/O Pins

The output DCD cycle only applies to the I/O buffer. It does not cover the system DCD.

Symbol	-C6		-C7, -I7		-C8, -A7		Unit
	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	%

HPS Specifications

This section provides HPS specifications and timing for Cyclone V devices.

For HPS reset, the minimum reset pulse widths for the HPS cold and warm reset signals (HPS_nRST and HPS_nPOR) are six clock cycles of HPS_CLK1.

HPS Clock Performance

Table 40. HPS Clock Performance for Cyclone V Devices

Symbol/Description	-C6	-C7, -I7	-A7	-C8	Unit
mpu_base_clk (microprocessor unit clock)	925	800	700	600	MHz
main_base_clk (L3/L4 interconnect clock)	400	400	350	300	MHz
h2f_user0_clk	100	100	100	100	MHz
h2f_user1_clk	100	100	100	100	MHz
h2f_user2_clk	200	200	160	160	MHz

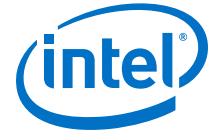
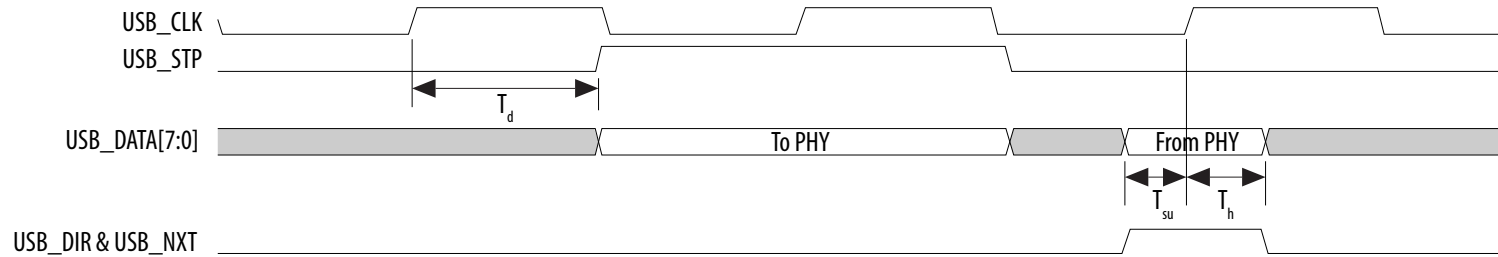


Figure 10. USB Timing Diagram

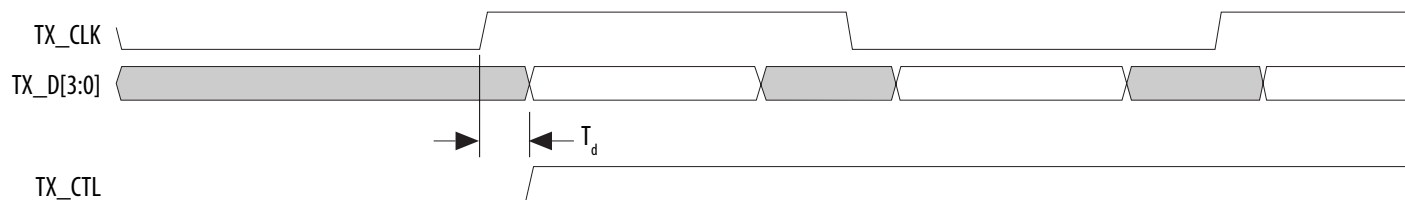


Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 48. Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Cyclone V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk} (1000Base-T)	TX_CLK clock period	—	8	—	ns
T_{clk} (100Base-T)	TX_CLK clock period	—	40	—	ns
T_{clk} (10Base-T)	TX_CLK clock period	—	400	—	ns
T_{duty}	TX_CLK duty cycle	45	—	55	%
T_d	TX_CLK to TXD/TX_CTL output data delay	-0.85	—	0.15	ns

Figure 11. RGMII TX Timing Diagram





POR Specifications

Table 55. Fast and Standard POR Delay Specification for Cyclone V Devices

POR Delay	Minimum	Maximum	Unit
Fast	4	12 ⁽⁷⁴⁾	ms
Standard	100	300	ms

Related Information

MSEL Pin Settings

Provides more information about POR delay based on MSEL pin settings for each configuration scheme.

FPGA JTAG Configuration Timing

Table 56. FPGA JTAG Timing Parameters and Values for Cyclone V Devices

Symbol	Description	Min	Max	Unit
t _{JCP}	TCK clock period	30, 167 ⁽⁷⁵⁾	—	ns
t _{JCH}	TCK clock high time	14	—	ns
t _{JCL}	TCK clock low time	14	—	ns
t _{JPSU (TDI)}	TDI JTAG port setup time	1	—	ns
t _{JPSU (TMS)}	TMS JTAG port setup time	3	—	ns
t _{JPH}	JTAG port hold time	5	—	ns

continued...

⁽⁷⁴⁾ The maximum pulse width of the fast POR delay is 12 ms, providing enough time for the PCIe hard IP to initialize after the POR trip.

⁽⁷⁵⁾ The minimum TCK clock period is 167 ns if V_{CCBAT} is within the range 1.2 V – 1.5 V when you perform the volatile key programming.



Configuration Scheme	Encryption	Compression	DCLK-to-DATA[] Ratio (r)
	On	Off	2
	Off	On	4
	On	On	4

FPP Configuration Timing when DCLK-to-DATA[] = 1

When you enable decompression or the design security feature, the DCLK-to-DATA[] ratio varies for FPP ×8 and FPP ×16. For the respective DCLK-to-DATA[] ratio, refer to the DCLK-to-DATA[] Ratio for Cyclone V Devices table.

Table 58. FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Cyclone V Devices

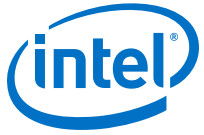
Symbol	Parameter	Minimum	Maximum	Unit
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μs
t _{STATUS}	nSTATUS low pulse width	268	1506 ⁽⁷⁷⁾	μs
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1506 ⁽⁷⁸⁾	μs
t _{CF2CK} ⁽⁷⁹⁾	nCONFIG high to first rising edge on DCLK	1506	—	μs
t _{ST2CK} ⁽⁷⁹⁾	nSTATUS high to first rising edge of DCLK	2	—	μs
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t _{CH}	DCLK high time	0.45 × 1/f _{MAX}	—	s

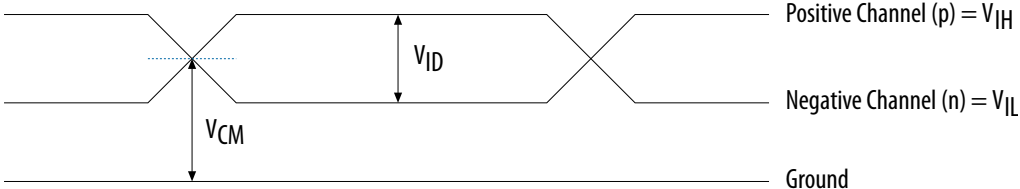
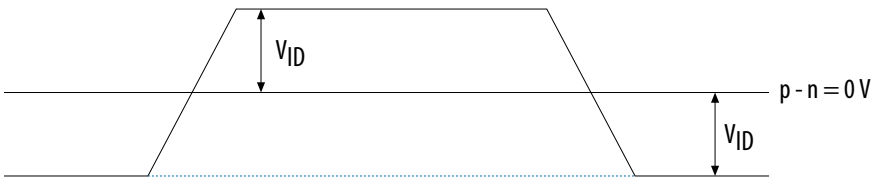
continued...

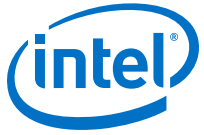
⁽⁷⁷⁾ You can obtain this value if you do not delay configuration by extending the nCONFIG or the nSTATUS low pulse width.

⁽⁷⁸⁾ You can obtain this value if you do not delay configuration by externally holding the nSTATUS low.

⁽⁷⁹⁾ If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

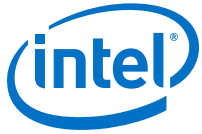


Term	Definition
	<p data-bbox="730 315 968 342">Single-Ended Waveform</p>  <p data-bbox="1507 365 1743 393">Positive Channel (p) = V_{IH}</p> <p data-bbox="1507 451 1743 479">Negative Channel (n) = V_{IL}</p> <p data-bbox="1507 527 1575 555">Ground</p> <p data-bbox="730 609 953 636">Differential Waveform</p>  <p data-bbox="1507 730 1596 758">$p - n = 0V$</p> <p data-bbox="594 862 884 889">Transmitter Output Waveforms</p> <p data-bbox="1738 915 1869 938"><i>continued...</i></p>



Term	Definition
	<p>The diagram shows the timing relationships between TMS, TDI, TCK, and TDO signals. TMS and TDI are shown as rectangular pulses. TCK is a clock signal with several cycles. TDO is a data signal that is sampled on the falling edge of TCK. The timing parameters are defined as follows:</p> <ul style="list-style-type: none"> t_{JCP}: Time from the rising edge of TCK to the rising edge of TMS. t_{JCH}: Time from the rising edge of TCK to the rising edge of TDI. t_{JCL}: Time from the rising edge of TCK to the falling edge of TDI. t_{JPSU}: Time from the rising edge of TCK to the rising edge of TDO. t_{JPH}: Time from the rising edge of TCK to the falling edge of TDO. t_{JPCO}: Time from the falling edge of TCK to the rising edge of TDO. t_{JPZX}: Time from the falling edge of TCK to the falling edge of TDO.
PLL specifications	Diagram of PLL specifications

continued...



Term	Definition
Single-ended voltage referenced I/O standard	<p>The JEDEC standard for the SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing.</p> <p>Single-Ended Voltage Referenced I/O Standard</p>
t_c	High-speed receiver/transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including the t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on high-speed transmitter output clock.
t_{FALL}	Signal high-to-low transition time (80–20%)
t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input
<i>continued...</i>	



Date	Version	Changes
December 2015	2015.12.04	<ul style="list-style-type: none"> • Updated Quad Serial Peripheral Interface (SPI) Flash Timing Requirements for Cyclone V Devices table. <ul style="list-style-type: none"> — Updated F_{clk}, $T_{dutycycle}$, and $T_{dssfrst}$ specifications. — Added T_{qspi_clk}, T_{din_start}, and T_{din_end} specifications. — Removed T_{dinmax} specifications. • Updated the minimum specification for T_{clk} to 16.67 ns and removed the maximum specification in SPI Master Timing Requirements for Cyclone V Devices table. • Updated Secure Digital (SD)/MultiMediaCard (MMC) Timing Requirements for Cyclone V Devices table. <ul style="list-style-type: none"> — Updated T_{clk} to $T_{sdmmc_clk_out}$ symbol. — Updated $T_{sdmmc_clk_out}$ and T_d specifications. — Added T_{sdmmc_clk}, T_{sur}, and T_h specifications. — Removed T_{dinmax} specifications. • Updated the following diagrams: <ul style="list-style-type: none"> — Quad SPI Flash Timing Diagram — SD/MMC Timing Diagram • Updated configuration .rbf sizes for Cyclone V devices. • Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
June 2015	2015.06.12	<ul style="list-style-type: none"> • Updated the supported data rates for the following output standards using true LVDS output buffer types in the High-Speed I/O Specifications for Cyclone V Devices table: <ul style="list-style-type: none"> — True RSDS output standard: data rates of up to 360 Mbps — True mini-LVDS output standard: data rates of up to 400 Mbps • Changed Queued Serial Peripheral Interface (QSPI) to Quad Serial Peripheral Interface (SPI) Flash. • Updated T_h location in I²C Timing Diagram. • Updated T_{wp} location in NAND Address Latch Timing Diagram. • Updated the maximum value for t_{CO} from 4 ns to 2 ns in AS Timing Parameters for AS ×1 and ×4 Configurations in Cyclone V Devices table. • Moved the following timing diagrams to the Configuration, Design Security, and Remote System Upgrades in Cyclone V Devices chapter. <ul style="list-style-type: none"> — FPP Configuration Timing Waveform When DCLK-to-DATA[] Ratio is 1 — FPP Configuration Timing Waveform When DCLK-to-DATA[] Ratio is >1 — AS Configuration Timing Waveform — PS Configuration Timing Waveform
March 2015	2015.03.31	<ul style="list-style-type: none"> • Added V_{CC} specifications for devices with internal scrubbing feature (with SC suffix) in Recommended Operating Conditions table. • Corrected the unit for t_{DH} from ns to s in FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Cyclone V Devices table.
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Date	Version	Changes
June 2013	3.4	<ul style="list-style-type: none"> • Updated Table 20, Table 27, and Table 34. • Updated "UART Interface" and "CAN Interface" sections. • Removed the following tables: <ul style="list-style-type: none"> — Table 45: UART Baud Rate for Cyclone V Devices — Table 47: CAN Pulse Width for Cyclone V Devices
May 2013	3.3	<ul style="list-style-type: none"> • Added Table 33. • Updated Figure 5, Figure 6, Figure 17, Figure 19, and Figure 20. • Updated Table 1, Table 4, Table 5, Table 10, Table 13, Table 19, Table 20, Table 26, Table 32, Table 35, Table 36, Table 43, Table 53, Table 54, Table 57, and Table 61.
March 2013	3.2	<ul style="list-style-type: none"> • Added HPS reset information in the "HPS Specifications" section. • Added Table 57. • Updated Table 1, Table 2, Table 17, Table 20, Table 52, and Table 56. • Updated Figure 18.
January 2013	3.1	Updated Table 4, Table 20, and Table 56.
November 2012	3.0	<ul style="list-style-type: none"> • Updated Table 1, Table 4, Table 5, Table 9, Table 14, Table 16, Table 17, Table 19, Table 20, Table 25, Table 28, Table 52, Table 55, Table 56, and Table 59. • Removed table: Transceiver Block Jitter Specifications for Cyclone V GX Devices. • Added HPS information: <ul style="list-style-type: none"> — Added "HPS Specifications" section. — Added Table 33, Table 34, Table 35, Table 36, Table 37, Table 38, Table 39, Table 40, Table 41, Table 42, Table 43, Table 44, Table 45, and Table 46. — Added Figure 4, Figure 5, Figure 6, Figure 7, Figure 8, Figure 9, Figure 10, Figure 11, Figure 12, Figure 13, Figure 14, Figure 15, and Figure 16. — Updated Table 3.
June 2012	2.0	<p>Updated for the Quartus Prime software v12.0 release:</p> <ul style="list-style-type: none"> • Restructured document. • Removed "Power Consumption" section. • Updated Table 1, Table 3, Table 19, Table 20, Table 25, Table 27, Table 28, Table 30, Table 31, Table 34, Table 36, Table 37, Table 38, Table 39, Table 41, Table 43, and Table 46. • Added Table 22, Table 23, and Table 29. • Added Figure 1 and Figure 2. • Added "Initialization" and "Configuration Files" sections.

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